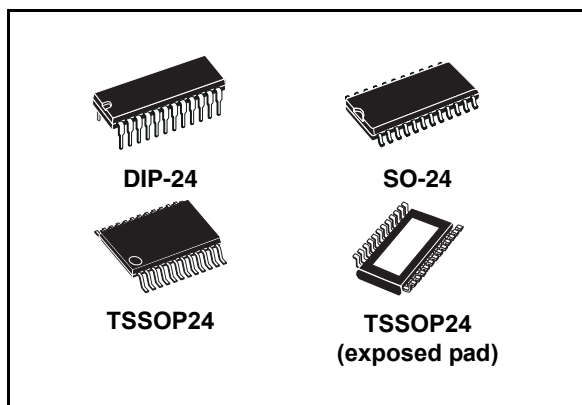


## Low voltage 16-Bit constant current LED sink driver

### Features

- Low voltage power supply down to 3V
- 16 constant current output channels
- Adjustable output current through external resistor
- Serial Data IN/Parallel Data OUT
- Can be driven by a 3.3V microcontroller
- Output current: 5-80mA
- Max clock frequency 30MHz
- ESD protection 2.5kV HBM, 200V MM



### Description

The STP16CP05 is a monolithic, low voltage, low current power 16-bit shift register designed for LED panel displays. The STP16CP05 contains a 16-bit serial-in, parallel-out shift register that feeds a 16-bit, D-type storage register. In the output stage, sixteen regulated current sources provide from 5mA to 80mA constant current to drive the LEDs.

The output current setup time is 40ns (typ), thus improving the system performance.

The LEDs' brightness can be controlled by using an external resistor to adjust the STP16CP05 output current.

The STP16CP05 guarantees a 20V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30MHz, makes the device suitable for high data rate transmission. The 3.3V voltage supply is useful in applications that interface with a 3.3V microcontroller.

### Order codes

Part number	Package	Packaging
STP16CP05B1R	DIP-24	15 parts per tube
STP16CP05MTR	SO-24	1000 parts per reel
STP16CP05TTR	TSSOP24	2500 parts per reel
STP16CP05XTR	TSSOP24 Exposed Pad	2500 parts per reel

# Contents

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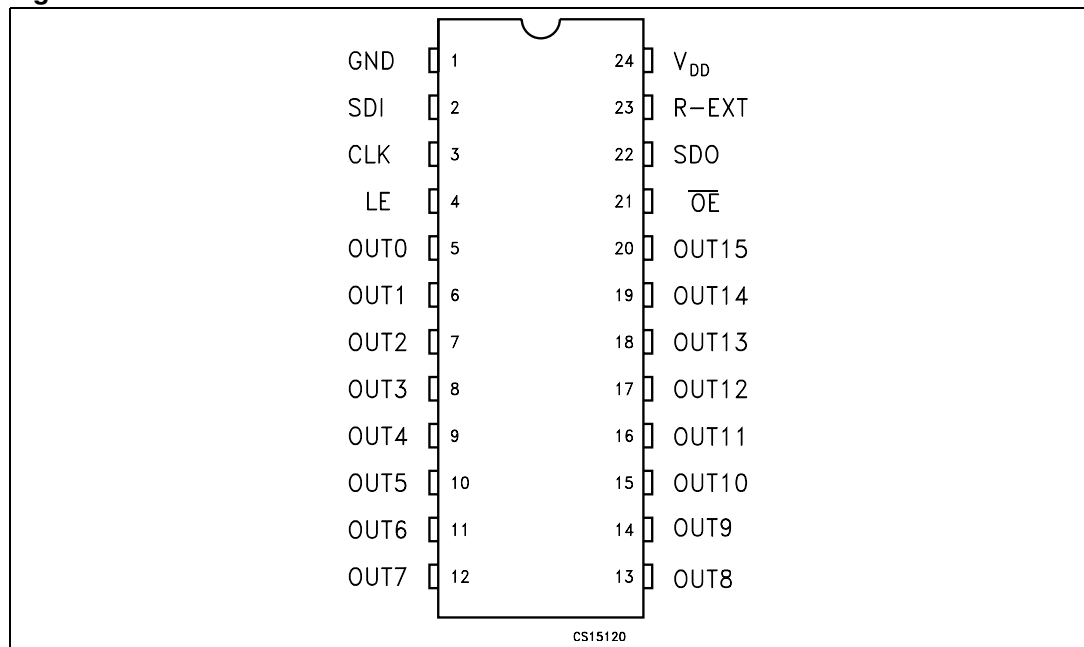
# 1 Summary description

**Table 1. Current accuracy**

Output voltage	Current accuracy		Output current	V <sub>DD</sub>	temp.
	Between bits	Between ICs			
≥ 1.0V	± 3%	± 8%	≥15 to 80 mA	3.3V to 5V	25°C
≥ 0.2V	± 6%	± 8%	5 to 15 mA		

## 1.1 Pin connection and description

**Figure 1. Pin connection**



*Note:* The exposed pad is electrically not connected

**Table 2. Pin description**

PIN N°	Symbol	Name and function
1	GND	Ground Terminal
2	SDI	Serial data input terminal
3	CLK	Clock input terminal
4	LE	Latch input terminal
5-20	OUT 0-15	Output terminal
21	$\overline{OE}$	Input terminal of output enable (active low)
22	SDO	Serial data out terminal
23	R-EXT	Input terminal of an external resistor for constant current programing
24	V <sub>DD</sub>	Supply voltage terminal

## 2 Electrical ratings

### 2.1 Absolute maximum ratings

Stressing the device above the rating listed in the “Absolute Maximum Ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

**Table 3. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DD}$	Supply voltage	0 to 7	V
$V_O$	Output voltage	-0.5 to 20	V
$I_O$	Output current	80	mA
$V_I$	Input voltage	-0.4 to $V_{DD}+0.4$	V
$I_{GND}$	GND terminal current	1300	mA
$f_{CLK}$	Clock frequency	50	MHz

### 2.2 Thermal data

**Table 4. Thermal data**

Symbol	Parameter	Value	Unit	
$T_{OPR}$	Operating temperature range	-40 to +125	°C	
$T_{STG}$	Storage temperature range	-55 to +150	°C	
$R_{thJC}$	Thermal resistance junction-case	DIP-24	60	°C/W
		TSSOP24	85	°C/W
		TSSOP24 <sup>(1)</sup> Exposed Pad	37.5	°C/W
		SO-24	75	°C/W

1. The exposed pad should be soldered directly to the PCB to realize the thermal benefits.

## 2.3 Recommended operating conditions

**Table 5. Recommended operating conditions at 25°C**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{DD}$	Supply voltage		3.0		5.5	V
$V_O$	Output voltage				20	V
$I_O$	Output current	OUTn	3		80	mA
$I_{OH}$	Output current	SERIAL-OUT			+1	mA
$I_{OL}$	Output current	SERIAL-OUT			-1	mA
$V_{IH}$	Input voltage		$0.7V_{DD}$		$V_{DD}+0.3$	V
$V_{IL}$	Input voltage		-0.3		$0.3V_{DD}$	V
$t_{wLAT}$	LE pulse width	$V_{DD} = 3.3V$ to $5.0V$	20			ns
$t_{wCLK}$	CLK pulse width		16			ns
$t_{wEN}$	/OE pulse width		200			ns
$t_{SETUP(D)}$	Setup time for DATA		20			ns
$t_{HOLD(D)}$	Hold time for DATA		15			ns
$t_{SETUP(L)}$	Setup time for LATCH		15			ns
$f_{CLK}$	Clock frequency		Cascade operation <sup>(1)</sup>			30

1. If the device is connected in cascade, it may not be possible to achieve the maximum data transfer. Please consider the timings carefully.

### 3 Electrical characteristics

**Table 6. Electrical characteristics**  
( $V_{DD} = 3.3V$  to  $5V$ ,  $T = 25^{\circ}C$ , unless otherwise specified.)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{IH}$	Input voltage high level		$0.7V_{DD}$		$V_{DD}$	V
$V_{IL}$	Input voltage low level		GND		$0.3V_{DD}$	V
$I_{OH}$	Output leakage current	$V_{OH} = 20V$			10	$\mu A$
$V_{OL}$	Output voltage (Serial-OUT)	$I_{OL} = 1mA$			0.4	V
$V_{OH}$	Output voltage (Serial-OUT)	$I_{OH} = -1mA$	$V_{DD}-0.4V$			V
$I_{OL1}$	Output current	$V_O = 0.3VR_{EXT} = 976\Omega$		20		mA
$I_{OL2}$		$V_O = 1.2VR_{EXT} = 241\Omega$		80		mA
$\Delta I_{OL1}$	Output current error between bit (All Output ON)	$V_O = 0.3VR_{EXT} = 976\Omega$		$\pm 2$	$\pm 3$	%
$\Delta I_{OL2}$		$V_O = 1.2VR_{EXT} = 241\Omega$		$\pm 2$	$\pm 3$	%
$R_{SIN(up)}$	Pull-up resistor		150	300	600	$K\Omega$
$R_{SIN(down)}$	Pull-down resistor		100	200	400	$K\Omega$
$I_{DD(OFF1)}$	Supply current (OFF)	$R_{EXT} = 970$ OUT 0 to 15 = OFF		4		mA
$I_{DD(OFF2)}$		$R_{EXT} = 240$ OUT 0 to 15 = OFF		11.2		
$I_{DD(ON1)}$	Supply current (ON)	$R_{EXT} = 970$ OUT 0 to 15 = ON		4.5		
$I_{DD(ON2)}$		$R_{EXT} = 240$ OUT 0 to 15 = ON		11.7		
Thermal	Thermal protection			170		$^{\circ}C$

**Table 7. Switching characteristics** ( $V_{DD} = 5V$ ,  $T = 25^{\circ}C$ , unless otherwise specified.)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$t_{PLH1}$	Propagation Delay Time, CLK-OUTn, LE = H, /OE = L	$V_{IH} = V_{DD}$ $V_{IL} = GND$ $I_O = 20mA$ $R_{EXT} = 1K\Omega$ $C_L = 10pF$ $V_L = 3.0 V$ $R_L = 60 \Omega$	$V_{DD} = 3.3V$	62	90	ns
			$V_{DD} = 5V$	39	55	
$t_{PLH2}$	Propagation Delay Time, LE-OUTn, /OE = L		$V_{DD} = 3.3V$	60	88	ns
			$V_{DD} = 5V$	41	57	
$t_{PLH3}$	Propagation Delay Time, /OE-OUTn, LE = H		$V_{DD} = 3.3V$	65	95	ns
			$V_{DD} = 5V$	43	60	
$t_{PLH}$	Propagation Delay Time, CLK-SDO		$V_{DD} = 3.3V$	8	12	ns
			$V_{DD} = 5V$	5	7	
$t_{PHL1}$	Propagation Delay Time, CLK-OUTn, LE = H, /OE = L		$V_{DD} = 3.3V$	18	25	ns
			$V_{DD} = 5V$	16	22	
$t_{PHL2}$	Propagation Delay Time, LE-OUTn, /OE = L		$V_{DD} = 3.3V$	19	25	ns
			$V_{DD} = 5V$	15	21	
$t_{PHL3}$	Propagation Delay Time, /OE-OUTn, LE = H		$V_{DD} = 3.3V$	23	31	ns
			$V_{DD} = 5V$	20	27	
$t_{PHL}$	Propagation Delay Time, CLK-SDO		$V_{DD} = 3.3V$	8.5	13	ns
			$V_{DD} = 5V$	5.5	8	
$t_{ON}$	Output Rise Time 10~90% of voltage waveform	$V_{DD} = 3.3V$	100	130	ns	
		$V_{DD} = 5V$	22	35		
$t_{OFF}$	Output Fall Time 90~10% of voltage waveform	$V_{DD} = 3.3V$	13	18	ns	
		$V_{DD} = 5V$	18	25		
$t_r$	CLK Rise Time <sup>(1)</sup>				5000	ns
$t_f$	CLK Fall Time <sup>(1)</sup>				5000	ns

1. In order to achieve high cascade data transfer, please consider tr/tf timings carefully.

# 4 Equivalent circuit and outputs

Figure 2.  $\overline{OE}$  Terminal

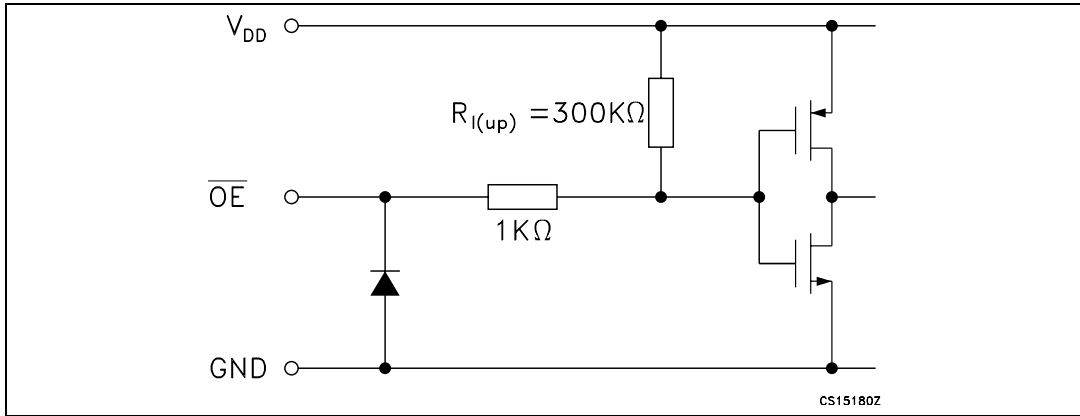


Figure 3. LE Terminal

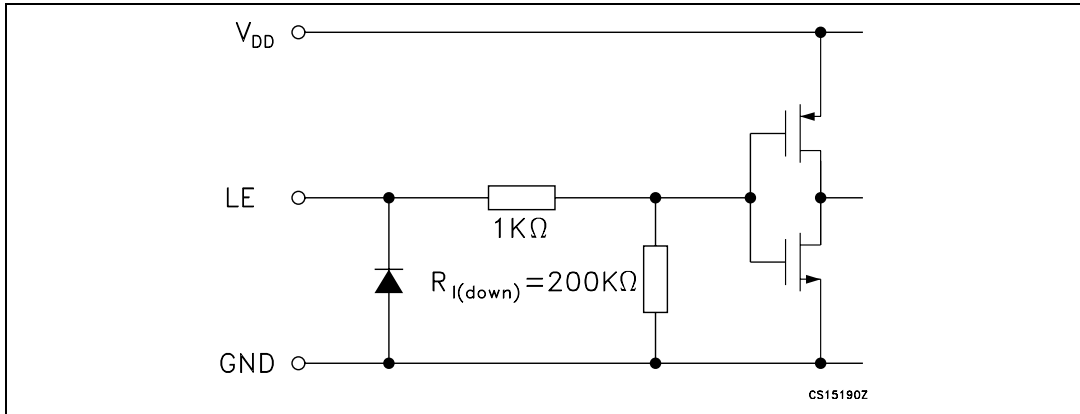


Figure 4. CLK, SDI Terminal

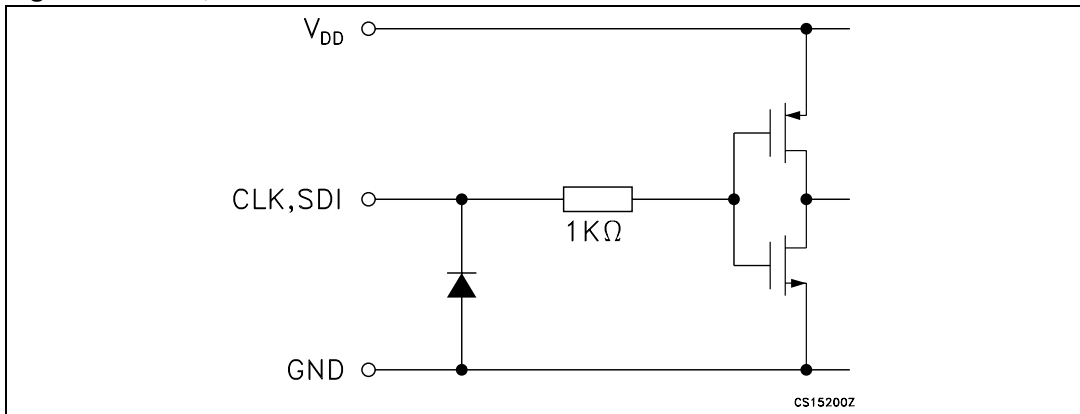




Figure 5. SDO Terminal

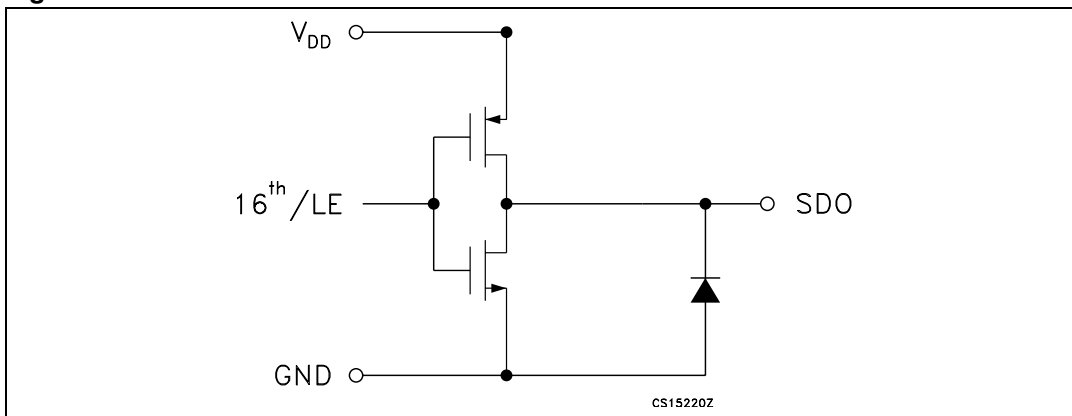
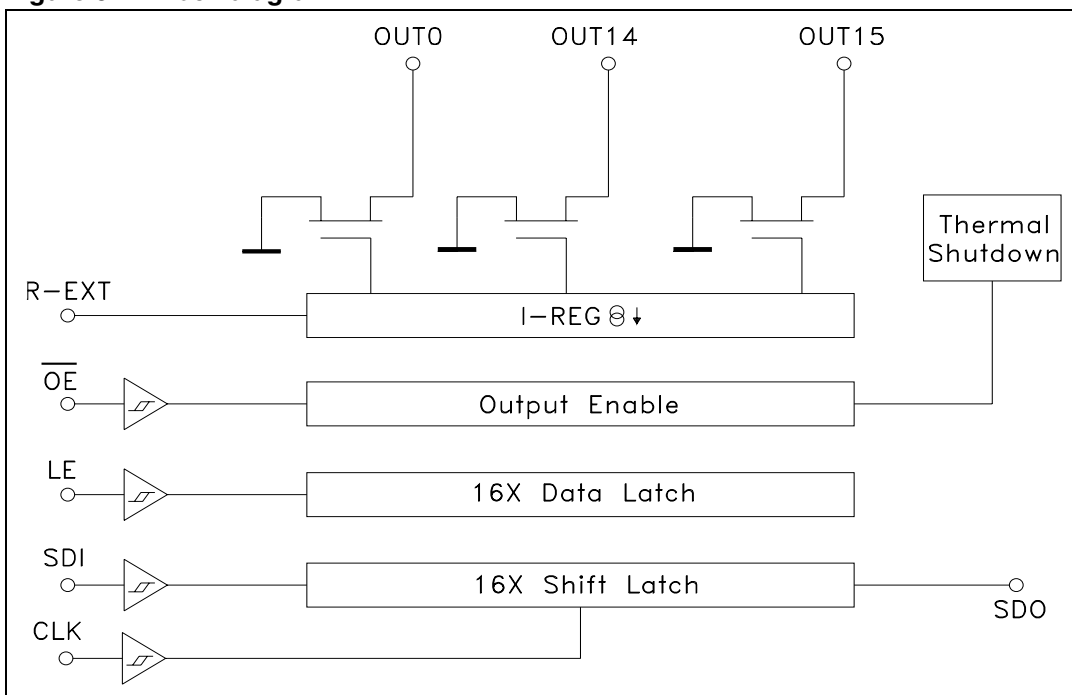


Figure 6. Block diagram



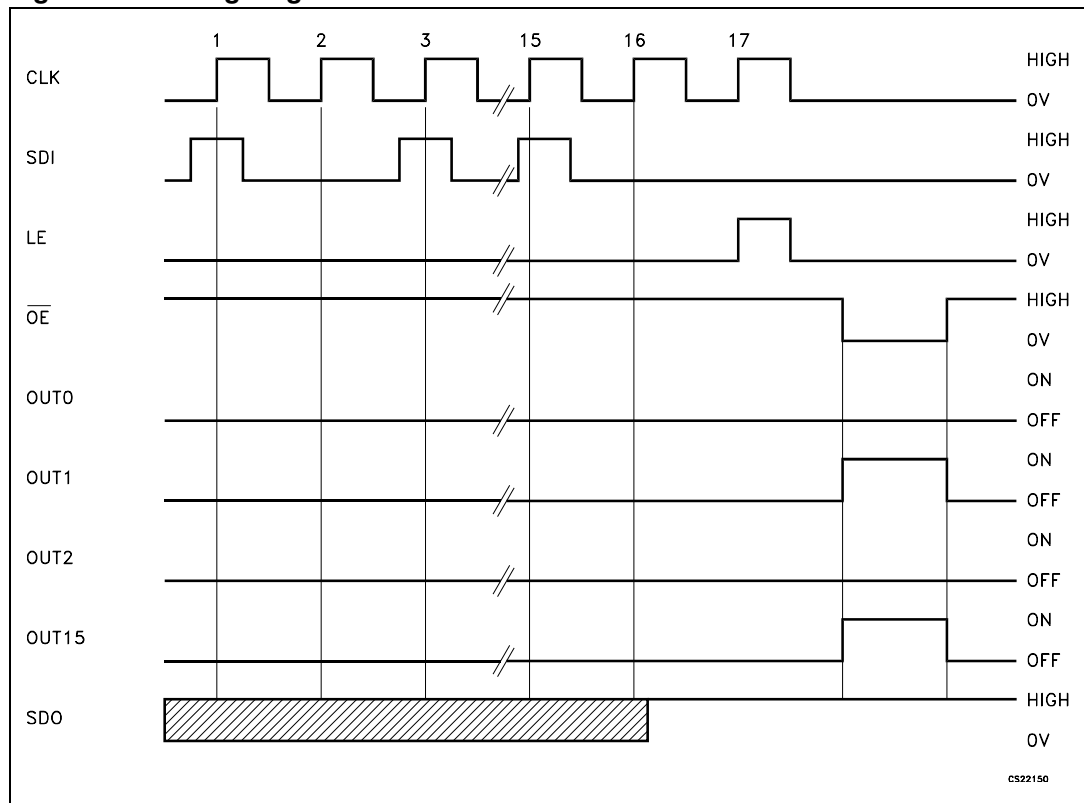
# 5 Timing diagrams

**Table 8. Truth Table**

CLOCK	LE	/OE	SERIAL-IN	OUT0 ..... OUT7 ..... OUT15	SDO
	H	L	Dn	Dn ..... Dn - 7 ..... Dn -15	Dn - 15
	L	L	Dn + 1	No Change	Dn - 14
	H	L	Dn + 2	Dn - 2 ..... Dn - 5 ..... Dn -13	Dn - 13
	X	L	Dn + 3	Dn - 2 ..... Dn - 5 ..... Dn -13	Dn - 13
	X	L	Dn + 3	ON	Dn - 13

Note: *OUT0 to OUT15 = ON when Dn = H; OUT0 to OUT15 = OFF when Dn = L.*

**Figure 7. Timing diagram**



Note: *The latches circuit holds data when the LE terminal is Low.*

- 1 *When LE terminal is at High level, latch circuit hold the data it passes from the input to the output.*
- 2 *When OE terminal is at Low level, output terminals OUT0 to OUT15 respond to the data, either ON or OFF.*
- 3 *When OE terminal is at High level, it switches off all the data on the output terminal.*

Figure 8. Clock, serial-in, serial-out

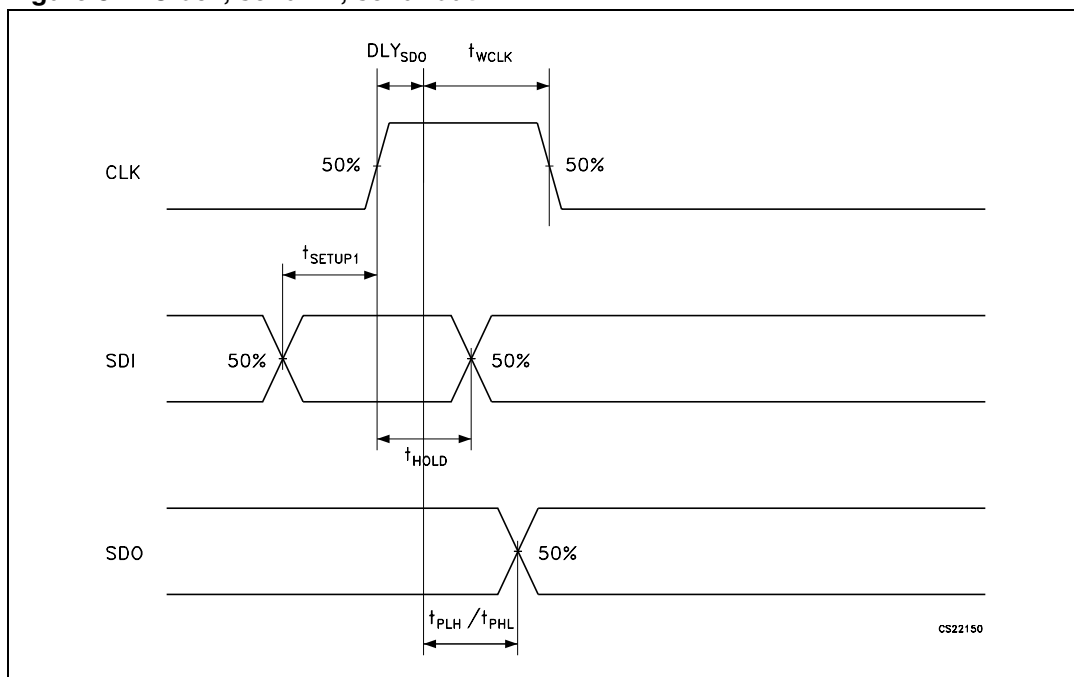


Figure 9. Clock, serial-in, latch, enable, outputs

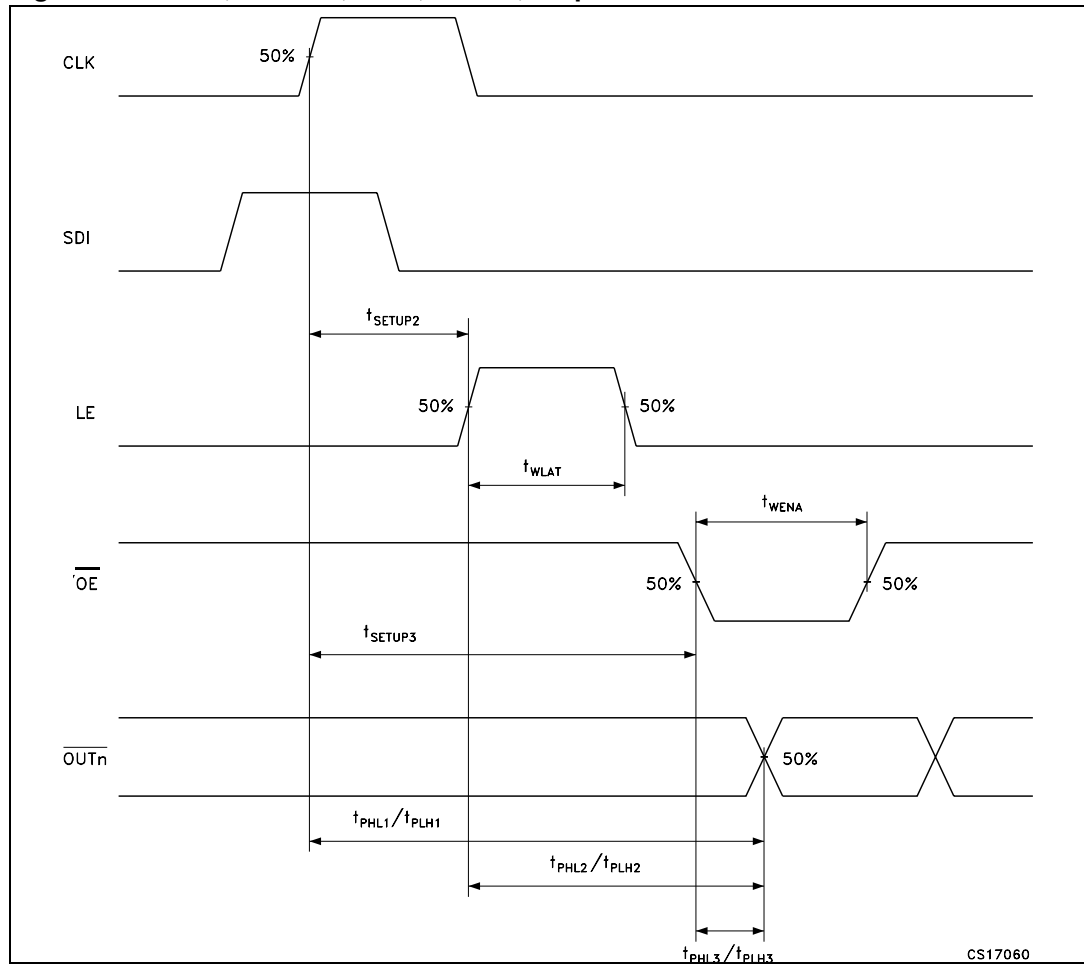
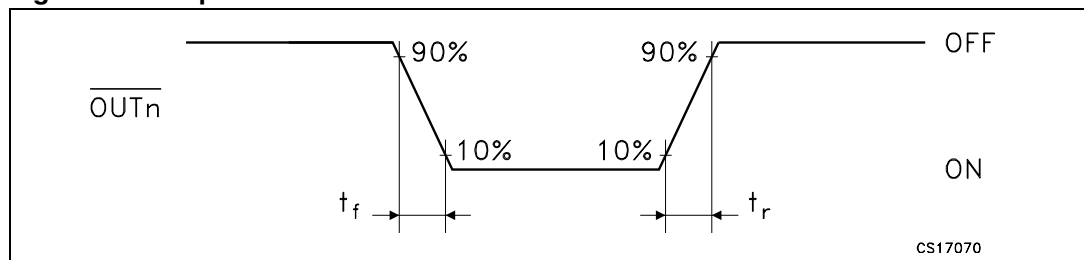


Figure 10. Outputs



## 6 Typical characteristics

Figure 11. Output current- $R_{EXT}$  resistor

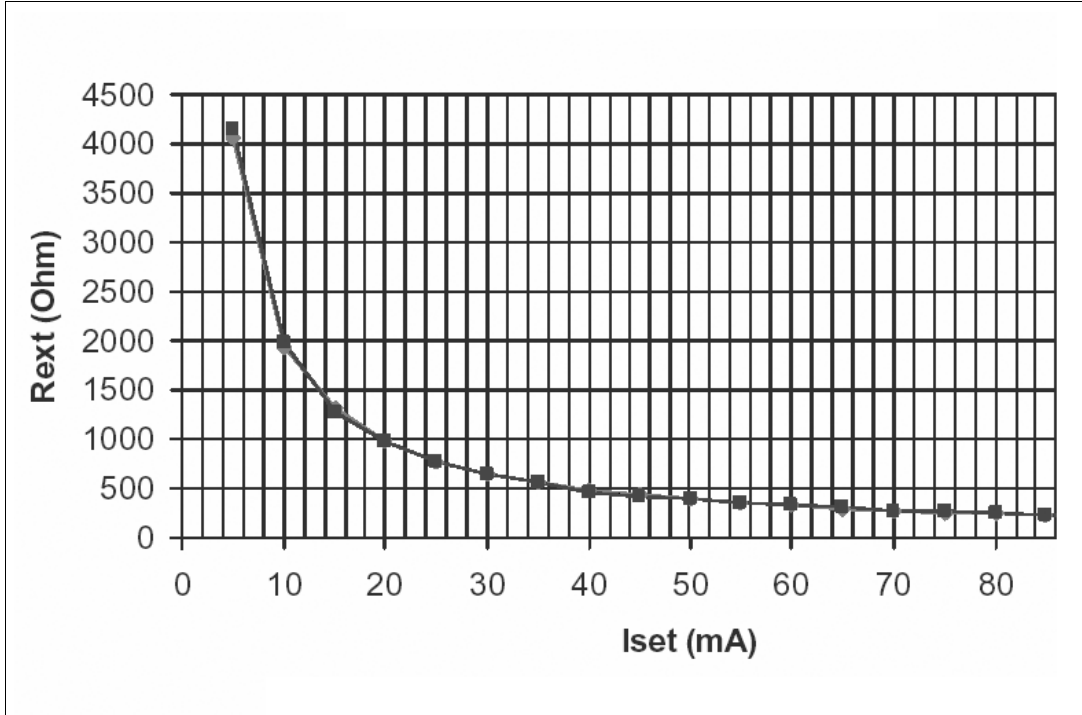


Table 9. Output current- $R_{EXT}$  resistor

Rext (Ohm)	Output current (mA)
976	20
780	25
652	30
560	35
488	40
433	45
389	50
354	55
325	60
300	65
278	70
259	75
241	80
229	85
215	90

Figure 12. Output current vs  $\pm \Delta I_{OL}(\%)$

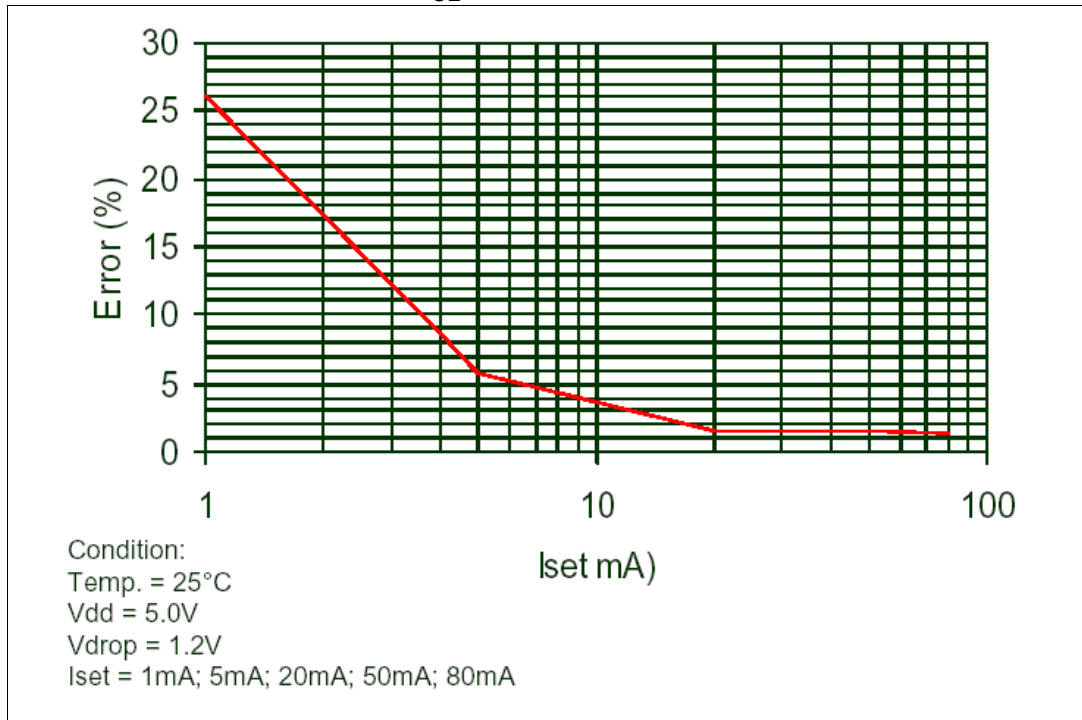


Figure 13. I<sub>SET</sub> vs drop out voltage (V<sub>drop</sub>)

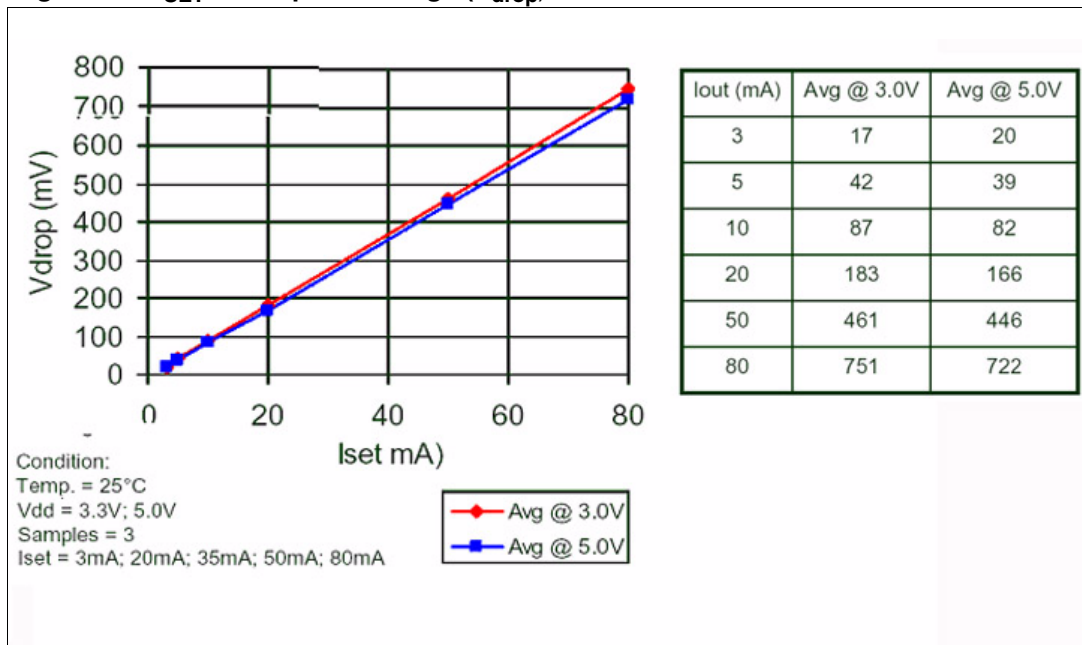
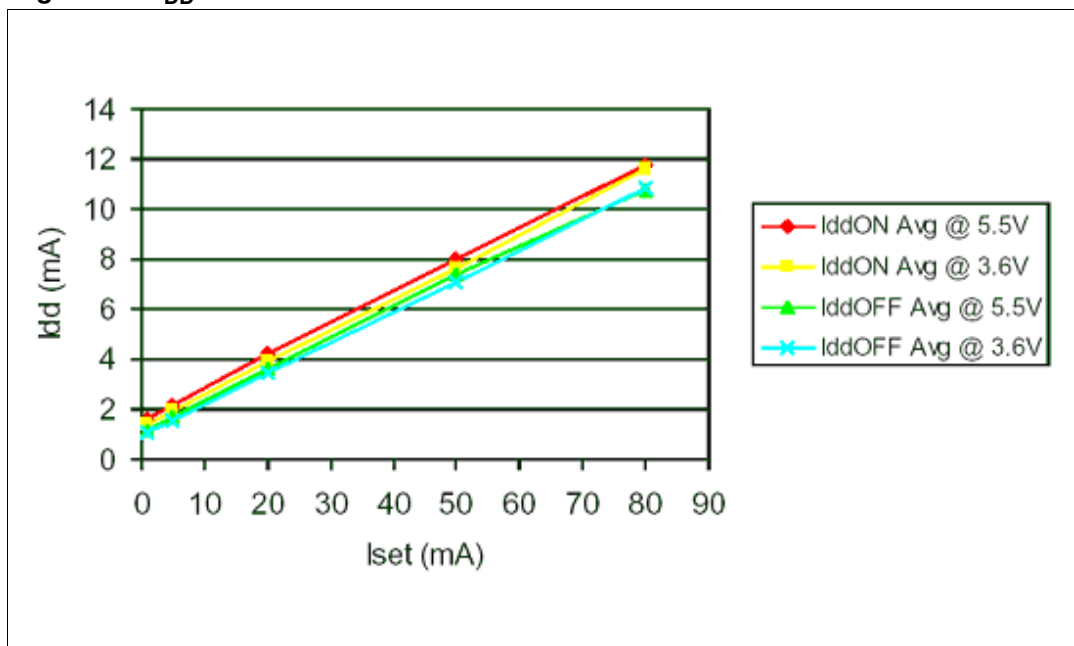


Figure 14.  $I_{DD}$  ON/OFF



# 7 Test circuit

Figure 15. DC characteristic

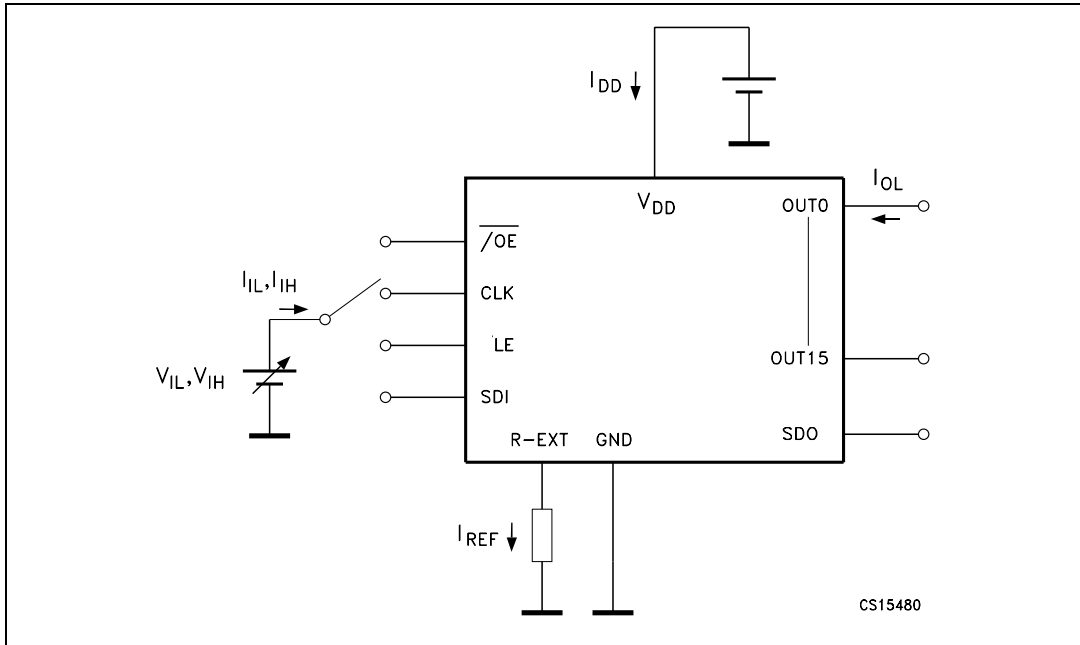


Figure 16. AC characteristic

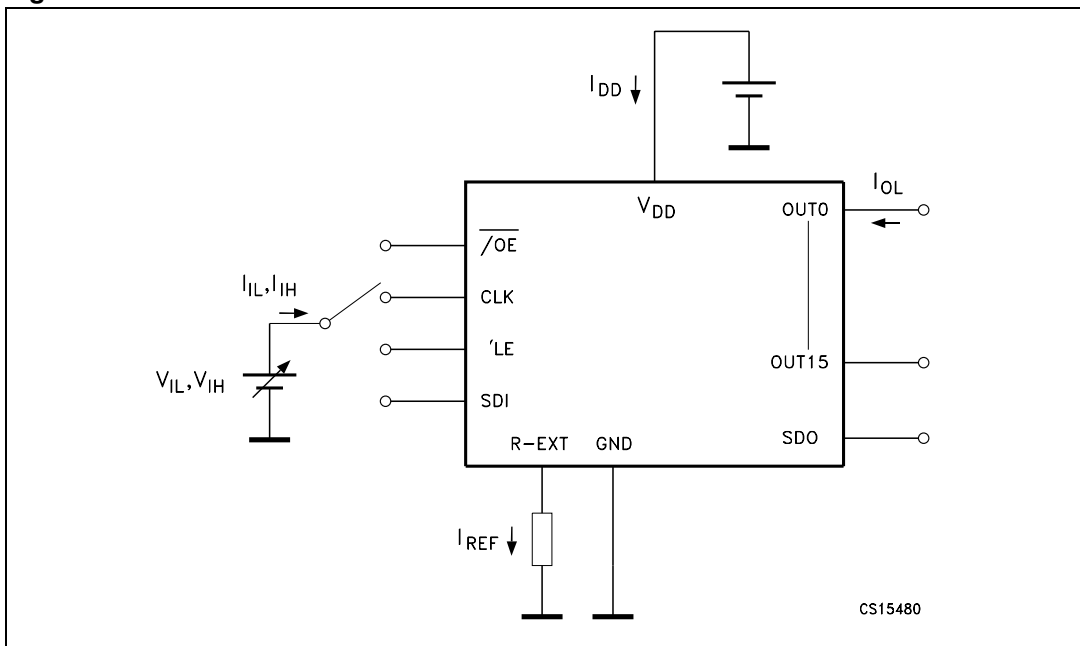
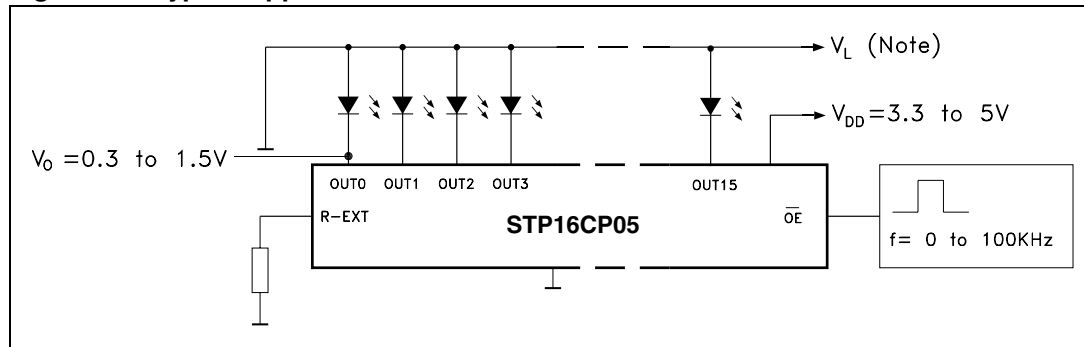




Figure 17. Typical application schematic



Note:  $V_L$  will be determined by the  $V_F$  of the LEDs

Test condition: Temp. = 25°C,  $V_{DD} = 3.0V$ ,  $V_{IN} = V_{DD}$ ,  $C_L = 10pF$ , Freq. = 1MHz, Ch1 = CLK, Ch2 = SDI, Ch3 = OUTn, Ch4 =  $V_{OUT}$

Figure 18. Turn ON output current setup

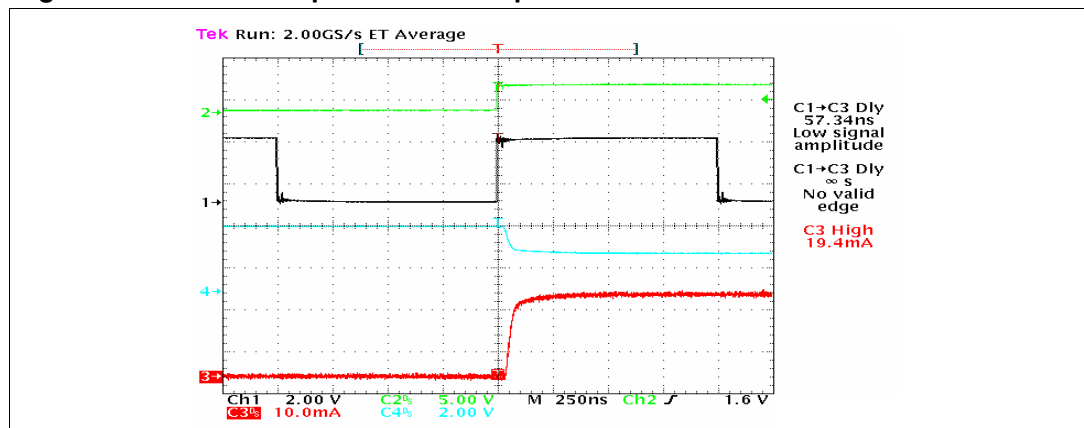
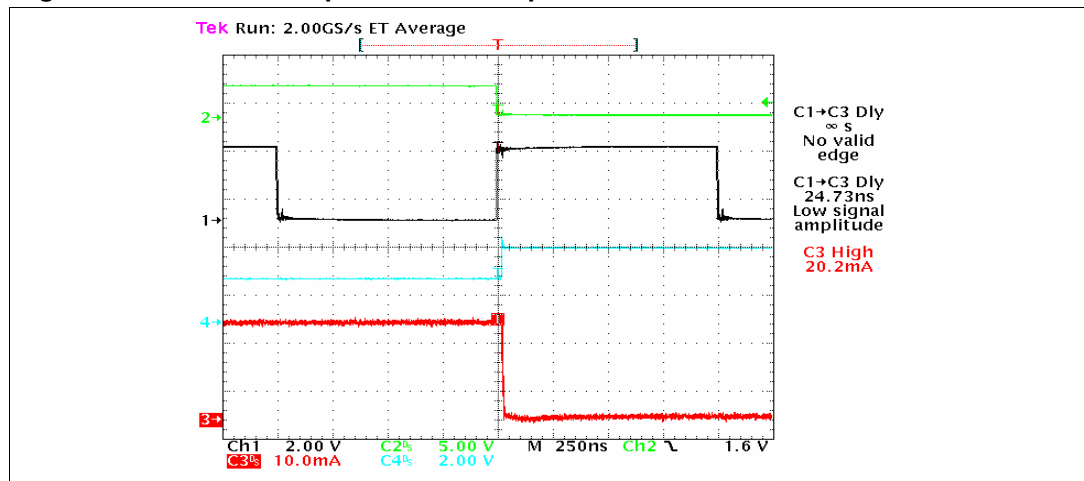


Figure 19. Turn OFF output current setup



## 8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

Table 10. Plastic DIP-24 (0.25) mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			4.32			0.170
A1	0.38			0.015		
A2		3.3			0.130	
B	0.41	0.46	0.51	0.016	0.018	0.020
B1	1.40	1.52	1.65	0.055	0.060	0.065
c	0.20	0.25	0.30	0.008	0.010	0.012
D	31.62	31.75	31.88	1.245	1.250	1.255
E	7.62		8.26	0.300		0.325
E1	6.35	6.60	6.86	0.250	0.260	0.270
e		2.54			0.100	
E1		7.62			0.300	
L	3.18		3.43	0.125		0.135
M	0°		15°	0°		15°

Figure 20. Plastic DIP-24 (0.25) package dimensions

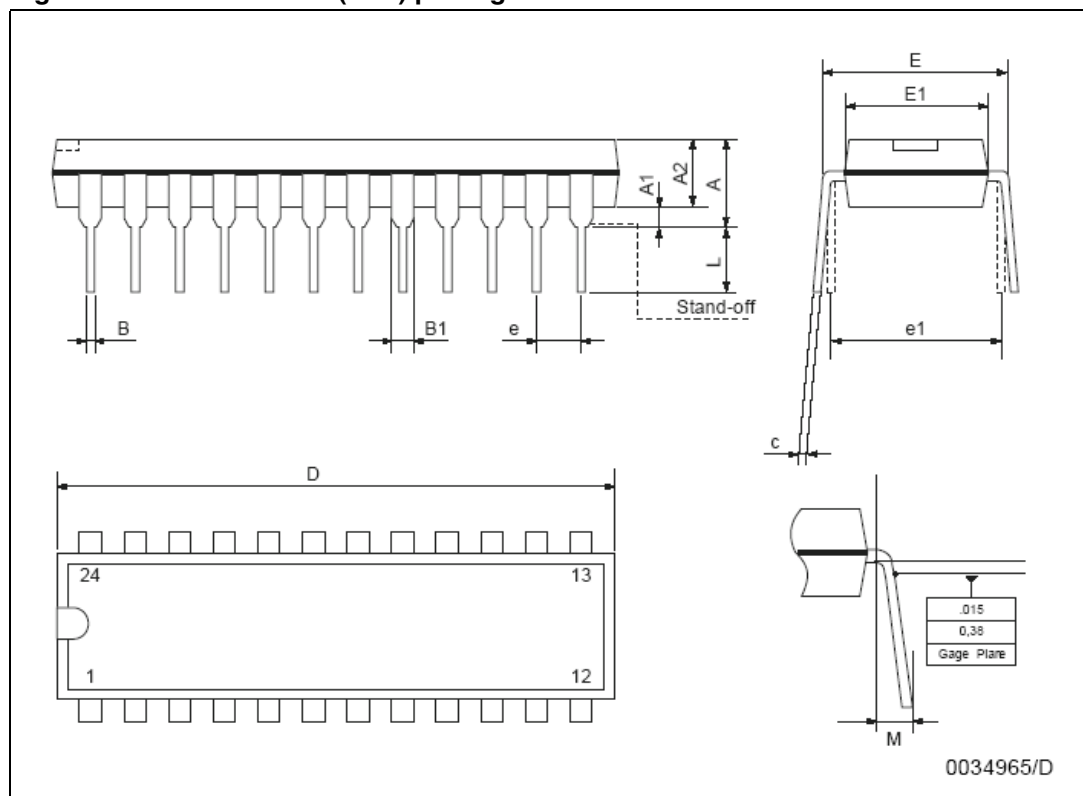


Table 11. TSSOP24 mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			1.1			0.043
A1	0.05		0.15	0.002		0.006
A2		0.9			0.035	
b	0.19		0.30	0.0075		0.0118
c	0.09		0.20	0.0035		0.0079
D	7.7		7.9	0.303		0.311
E	4.3		4.5	0.169		0.177
e		0.65 BSC			0.0256 BSC	
H	6.25		6.5	0.246		0.256
K	0°		8°	0°		8°
L	0.50		0.70	0.020		0.028

Figure 21. TSSOP24 Package dimensions

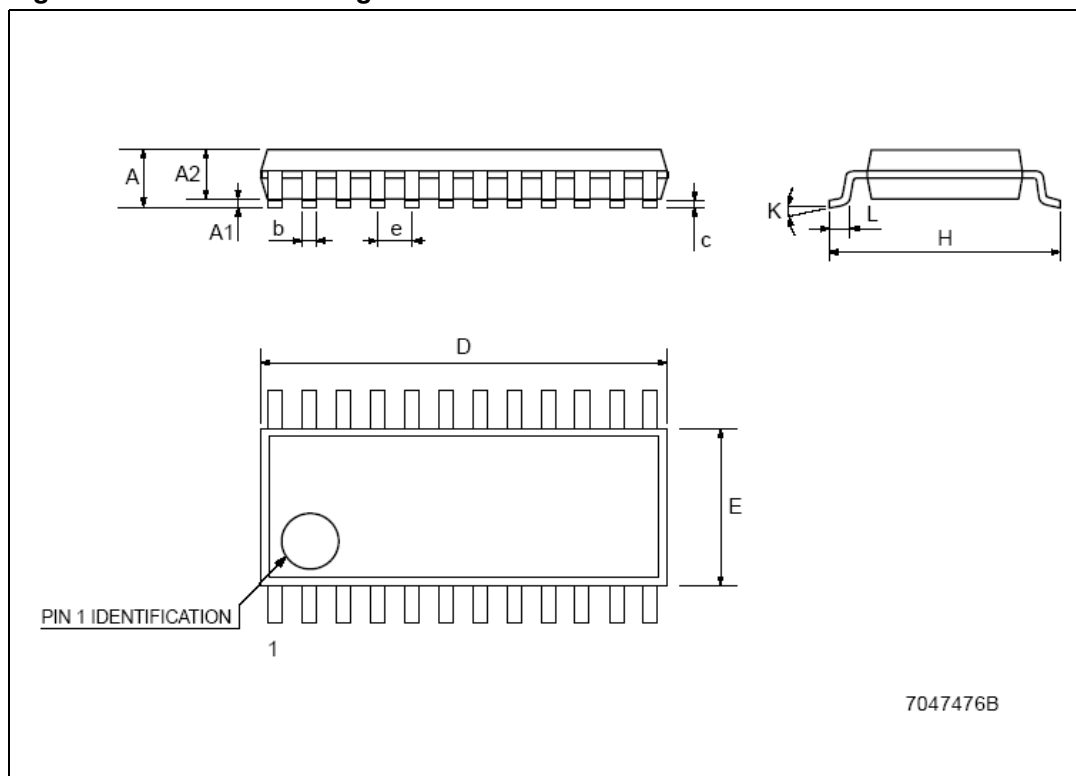


Table 12. Tape &amp; Reel TSSOP24

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.8		7	0.268		0.276
Bo	8.2		8.4	0.323		0.331
Ko	1.7		1.9	0.067		0.075
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476

Figure 22. Reel dimensions

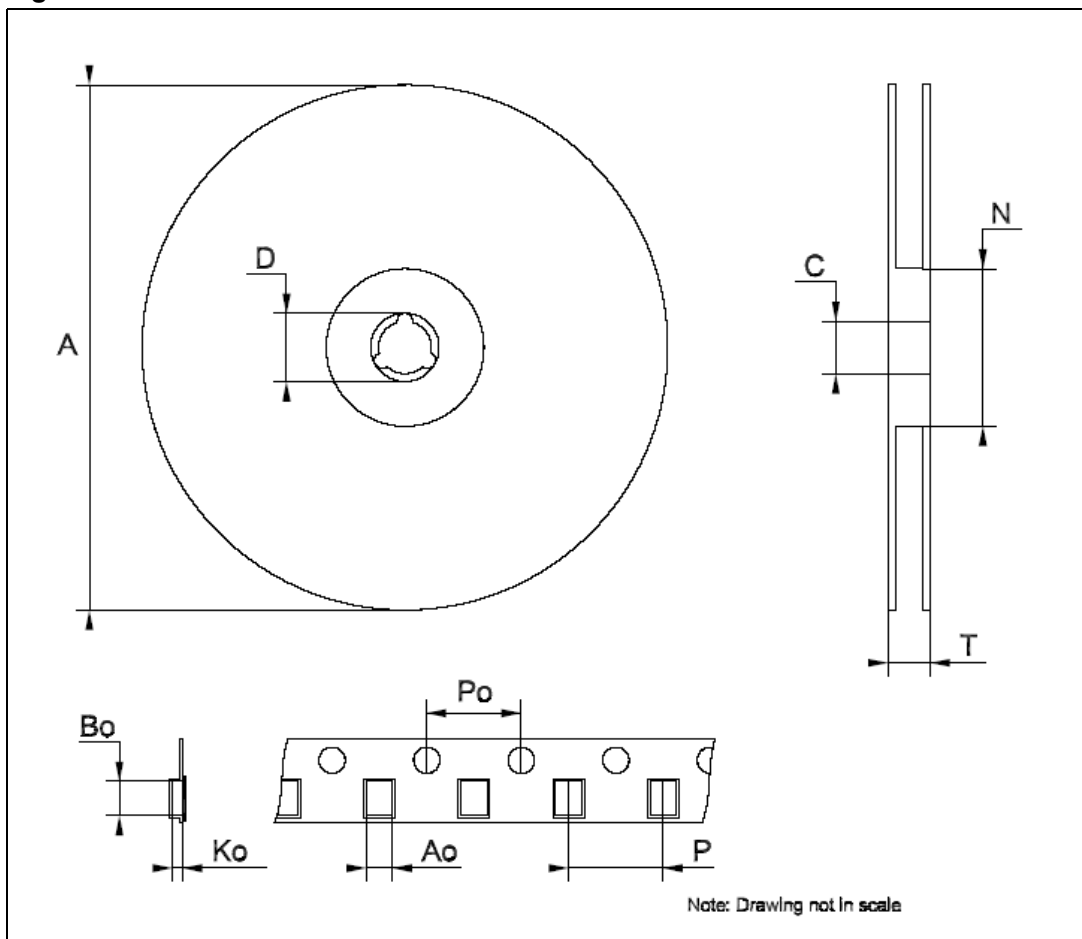
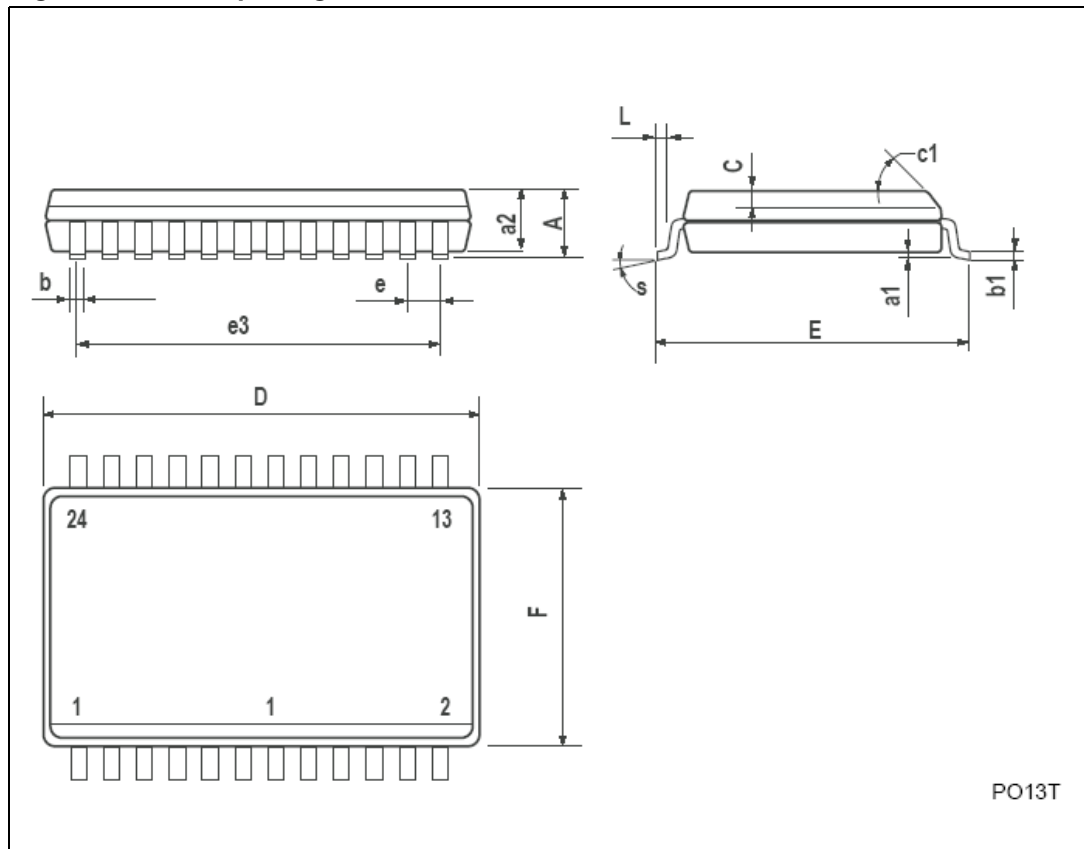


Table 13. SO-24 mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			2.65			0.104
a1	0.1		0.2	0.004		0.008
a2			2.45			0.096
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.012
C		0.5			0.020	
c1	45°(typ.)					
D	15.20		15.60	0.598		0.614
E	10.00		10.65	0.393		0.419
e		1.27			0.050	
e3		13.97			0.550	
F	7.40		7.60	0.291		0.300
L	0.50		1.27	0.020		0.050
S	°(max.) 8					

Figure 23. SO-24 package dimensions



PO13T

Table 14. Tape & Reel SO-24

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			30.4			1.197
Ao	10.8		11.0	0.425		0.433
Bo	15.7		15.9	0.618		0.626
Ko	2.9		3.1	0.114		0.122
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476

Figure 24. Reel dimensions

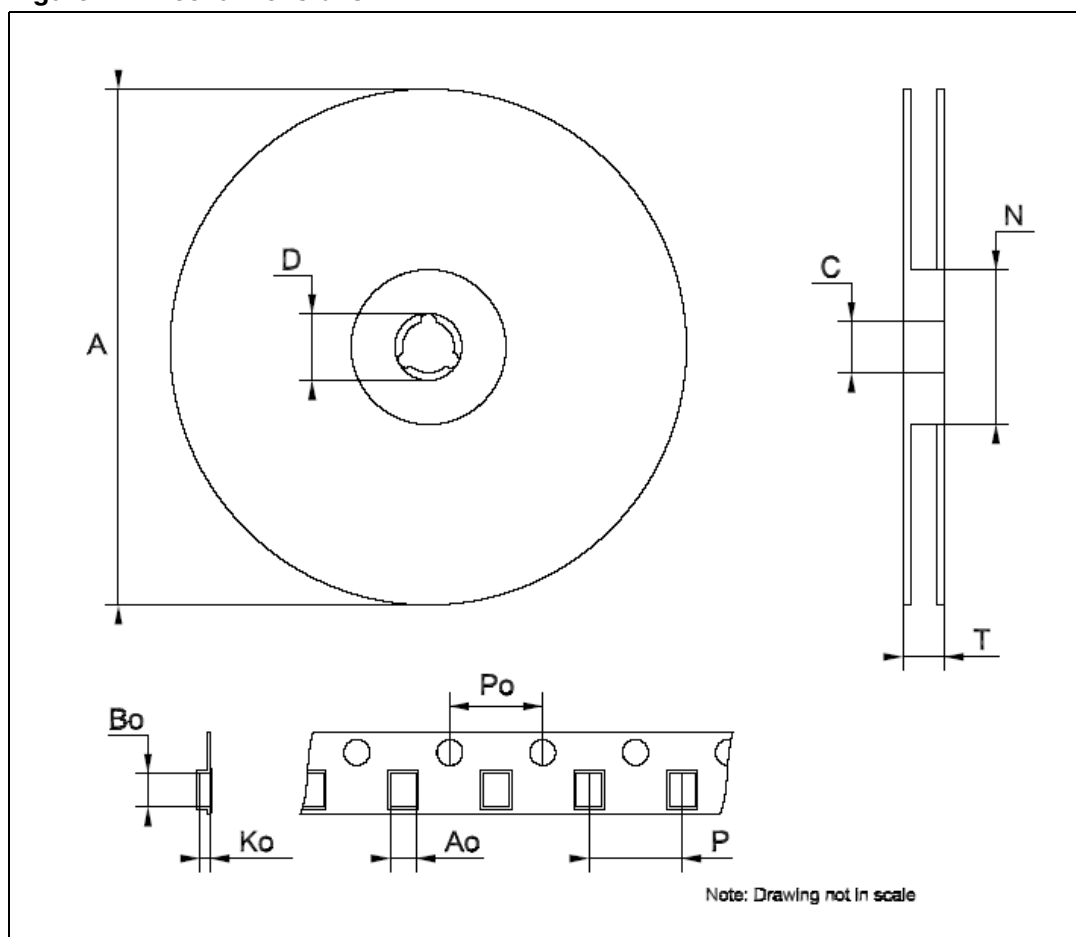
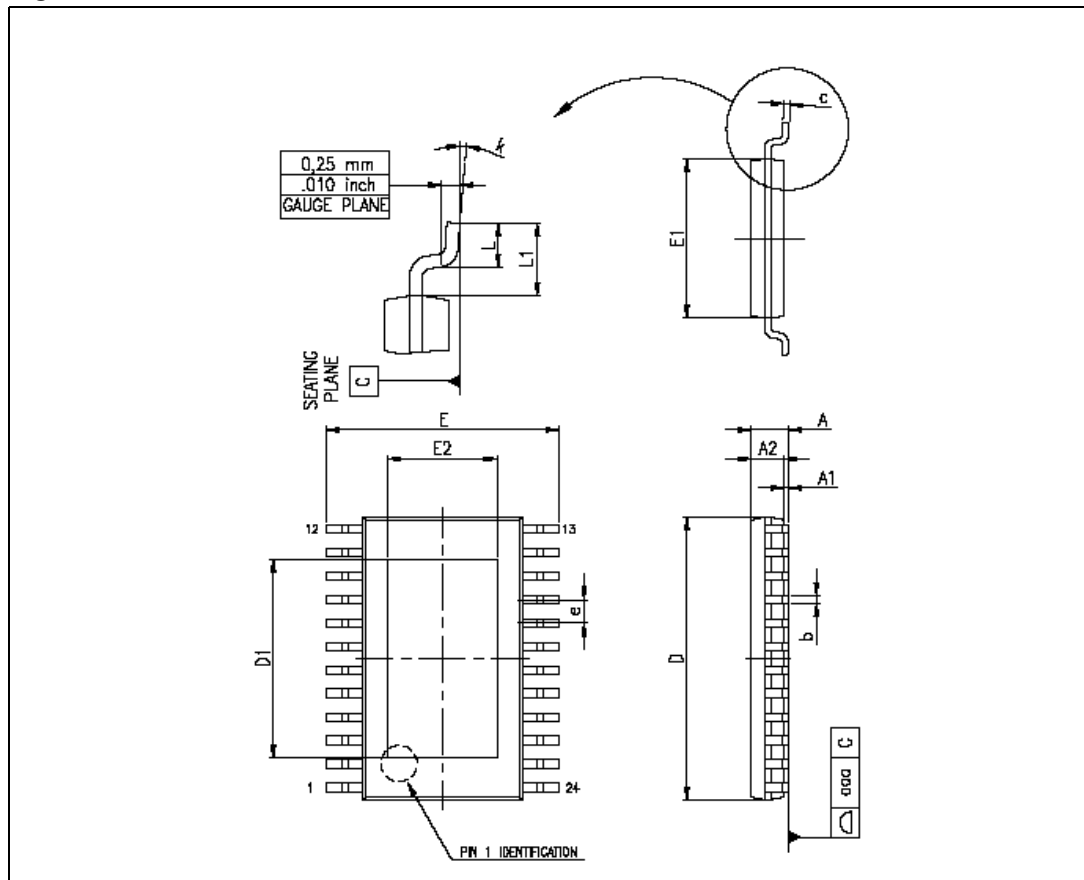


Table 15. TSSOP24 exposed-pad

Dim.	mm			inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1			0.15		0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	7.7	7.8	7.9	0.303	0.307	0.311
D1		2.7		0.106		
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.5	0.169	0.173	0.177
E2		1.5		0.059		
e		0.65			0.0256	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

Figure 25. TSSOP24 Dimensions





## 9 Revision history

**Table 16. Revision history**

<b>Date</b>	<b>Revision</b>	<b>Changes</b>
28-Jul-2006	1	First release
21-Dec-2006	2	Final datasheet

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